

# 金锡焊膏

Gold tin solder paste

## FH-280

FH-280 系列是共晶（熔点 280°C）金锡焊膏，产品具有高抗拉强度、耐腐蚀、高熔点、热蠕变性能好，同其他贵金属兼容及优良的导电、导热等特性，同时可实现印刷（FH-280P 系列）与点胶（FH-280D 系列）工艺。

FH-280 series is a eutectic (melting point 280°C) gold-tin solder paste. The product has high tensile strength, corrosion resistance, high melting point, good thermal creep performance, compatibility with other precious metals and excellent electrical and thermal conductivity. It can also achieve printing (FH-280P series) and dispensing (FH-280D series) process



### 特性 Features



**高熔点 (280°C) 焊膏, 高抗拉强度**

High melting point (280°C) solder paste, high tensile strength



**抗氧化, 耐腐蚀, 并兼容其它贵金属**

Anti-oxidation, corrosion resistance, compatible with other precious metals



**优良的导热、导电性能, 符合RoHS标准**

Excellent thermal and electrical conductivity, in line with RoHS standards



**触变性好, 粘度合适, 良好的润湿性与焊接性能**

Good thixotropy, suitable viscosity, good wettability and solderability



**微电子与半导体在阶梯回流焊接时, 首选的封装焊接材料**

The preferred package soldering material for microelectronics and semiconductors in step reflow soldering



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## 性能参数 Parameter

产品名称 Product	FH-2803P	FH-2804P	FH-2805P	FH-2806P	FH-2803D	FH-2804D	FH-2805D	FH-2806D
锡粉尺寸 Size	T3	T4	T5	T6	T3	T4	T5	T6
D50	30 $\mu$ m	27 $\mu$ m	20 $\mu$ m	9.5 $\mu$ m	30 $\mu$ m	27 $\mu$ m	20 $\mu$ m	9.5 $\mu$ m
涂覆方法 Using method	印刷 / printing				点胶或针转移 Dispensing, Pin transfer			
产品包装 Packaging	罐装/Canned 100g, 200g				针筒装/Syringe 2g, 5g, 10g, 20g			
合金组成 Alloy	Au80Sn20				Au80Sn20			
熔点 Melting point	280 $^{\circ}$ C				280 $^{\circ}$ C			
粘度 Pa.s	100~140				30~70			
Ti值	0.5~0.7				0.5~0.7			
合金比例 Alloy %	86~92%				84~90%			
助焊剂比例 Flux %	8~14%				10~16%			
铜板腐蚀 Corrosion	Pass <input checked="" type="checkbox"/>				Pass <input checked="" type="checkbox"/>			
锡珠测试 Solder ball	OK <input checked="" type="checkbox"/>				OK <input checked="" type="checkbox"/>			
残留物干燥度 Residue dryness	OK JIS Z 3284				OK JIS Z 3284			
卤素含量 Halogen content	无卤素 氯元素或溴元素小于900 ppm, 总量小于1500 ppm Halogen free Cl or Br <900 ppm, total <1500 ppm							

\*可按客户需求进行粒度、焊膏粘度及产品特殊应用进行定制。Can be customized the particle size, solder paste viscosity and product special applications.

## 产品应用

### Product Application

适用于半导体与微电子光电器件的高可靠性封装、大功率器件的高导热封装领域，及在阶梯回流焊接中的初级回流焊接应用，可避免二次回流焊接中的焊点溶化与失效，同时已在军工、航天航空、医疗等领域广泛应用。

Suitable for high-reliability packaging of semiconductors and microelectronics optoelectronic devices, high thermal conductivity packaging of high-power devices, and primary reflow soldering applications in step reflow soldering. It can avoid the melting and failure of solder joints in secondary reflow soldering. Has been widely used in military industry, aerospace, medical and other fields.

## 注意事项 Precautions

### 01 过回流焊/Reflow soldering

回流峰值温度高于熔点 (280 $^{\circ}$ C) 的温度 25~45 $^{\circ}$ C  
25 $^{\circ}$ C~ 45 $^{\circ}$ C above Melting Temperature.

氮气回流参考值 / Reference value of nitrogen reflux

< 200PPM

T5 在氮气回流中氧气

Type 5 Reflow in N<sub>2</sub> with < 200ppm O<sub>2</sub>

< 100PPM

T6 在氮气回流中氧气

Type 6 Reflow in N<sub>2</sub> with <100 ppm O<sub>2</sub>

### 02 产品储存/Product storage

冰箱储存温度在 0~10 $^{\circ}$ C 的条件  
Store at 0~10 $^{\circ}$ C